



# GL2N7002K

## GL Silicon N-Channel Power MOSFET

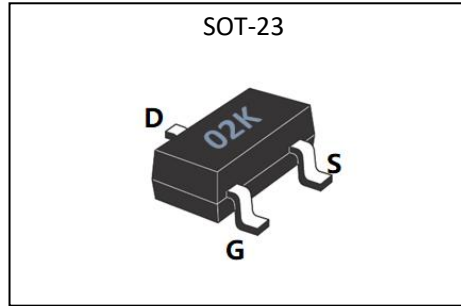
### General Description

The GL2N7002K uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. The package form is SOT-23, which accords with the RoHS standard.

$V_{DSS}$	60	V
$I_D$	0.3	A
$P_D$	0.35	W
$R_{DS(ON)max}$	2.5	$\Omega$

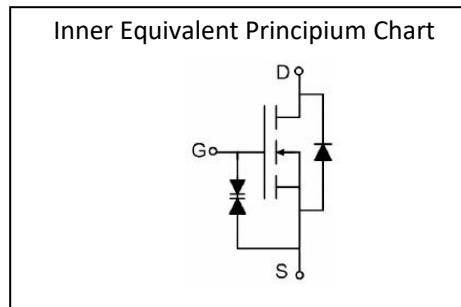
### Features

- Fast Switching
- Low Gate Charge and  $R_{dson}$
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test



### Applications

- PWM applications
- Load switch
- Power management



### Absolute (Tc=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-to-Source Voltage	60	V
$I_D$	Continuous Drain Current	0.3	A
	Continuous Drain Current $T_C = 100\text{ }^\circ\text{C}$	0.19	A
$I_{DM}^{a1}$	Pulsed Drain Current	0.9	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$dv/dt^{a3}$	Peak Diode Recovery $dv/dt$	5.0	V/ns
$P_D$	Power Dissipation	0.35	W
VESD(G-S)	Gate source ESD (HBM-C= 100pF, R=1.5k $\Omega$ )	2000	V
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	150, -55 to 150	$^\circ\text{C}$
$T_L$	Maximum Temperature for Soldering	300	$^\circ\text{C}$

Caution Stresses greater than those in the "Absolute Maximum Ratings" may cause permanent damage to the device



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**Electrical Characteristics** (Tc= 25°C unless otherwise specified)

OFF Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$V_{DSS}$	Drain to Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	60	--	--	V
$\Delta BV_{DSS}/\Delta T_J$	Bvdss Temperature Coefficient	$I_D=-250\mu A, \text{Reference } 25^\circ C$	--	0.1	--	V/°C
$I_{DSS}$	Drain to Source Leakage Current	$V_{DS}=60V, V_{GS}=0V, T_a=25^\circ C$	--	--	1	$\mu A$
		$V_{DS}=48V, V_{GS}=0V, T_a=125^\circ C$	--	--	250	
$I_{GSS(F)}$	Gate to Source Forward Leakage	$V_{GS}=+20V$	--	--	10	$\mu A$
$I_{GSS(R)}$	Gate to Source Reverse Leakage	$V_{GS}=-20V$	--	--	-10	$\mu A$

ON Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=10V, I_D=0.5A$	--	--	2.5	$\Omega$
$R_{DS(ON)}$	Drain-to-Source On-Resistance	$V_{GS}=4.5V, I_D=0.3A$	--	--	3.5	$\Omega$
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.7	2.5	V
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

Dynamic Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$g_{fs}$	Forward Transconductance	$V_{DS}=10V, I_D=0.2A$	0.1	5.0	--	S
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=15V$ $f=1.0MHz$	--	20	--	$\mu F$
$C_{oss}$	Output Capacitance		--	12	--	
$C_{riss}$	Reverse Transfer Capacitance		--	4.4	--	

Resistive Switching Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$t_{d(ON)}$	Turn-on Delay Time	$I_D=0.2A, V_{DD}=15V$ $V_{GS}=10V, R_G=3.0\Omega$	--	10	--	ns
$t_r$	Rise Time		--	45	--	
$t_{d(OFF)}$	Turn-Off Delay Time		--	15	--	
$t_f$	Fall Time		--	10	--	
$Q_g$	Total Gate Charge	$I_D=0.3A, V_{DD}=15V$ $V_{GS}=10V$	--	1.7	--	nC
$Q_{gs}$	Gate to Source Charge		--	0.9	--	
$Q_{gd}$	Gate to Drain ( "Miller" )Charge		--	1.3	--	



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Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
$I_S$	Continuous Source Current (Body Diode)		--	--	0.3	A
$I_{SM}$	Maximum Pulsed Current (Body Diode)		--	--	0.9	A
$V_{SD}$	Diode Forward Voltage	$I_S=0.3A, V_{GS}=0V$	--	--	1.5	V
$t_{rr}$	Reverse Recovery Time	$I_S=0.3A, T_j = 25^\circ C$	--	40	--	ns
$Q_{rr}$	Reverse Recovery Charge	$di_f/dt=100A/us, V_{GS}=0V$	--	120	--	nC
Pulse width $t_p \leq 380\mu s, \delta \leq 2\%$						

### Thermal Characteristics

Symbol	Parameter	Typ.	Units
$R_{\theta JA}$	Junction-to-Ambient	350	$^\circ C/W$

<sup>a1</sup>: Repetitive rating; pulse width limited by maximum junction temperature

<sup>a3</sup>:  $I_{SD}=0.3A, di/dt \leq 100A/us, V_{DD} \leq BV_{DS}, Start T_j=25^\circ C$



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### Typical Electrical And Thermal Characteristics

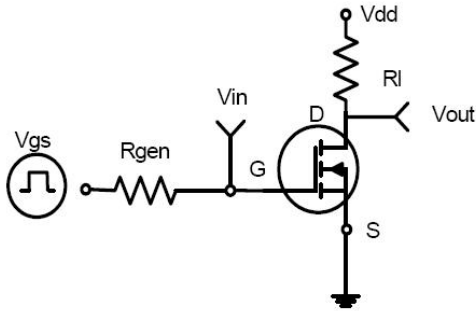


Figure 1: Switching Test Circuit

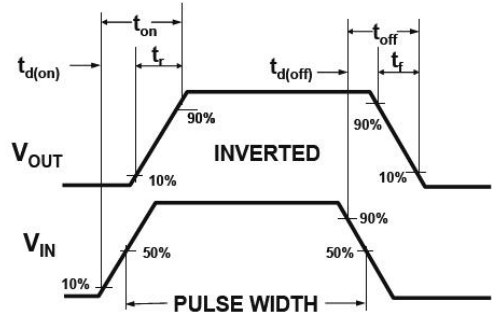


Figure 2: Switching Waveforms

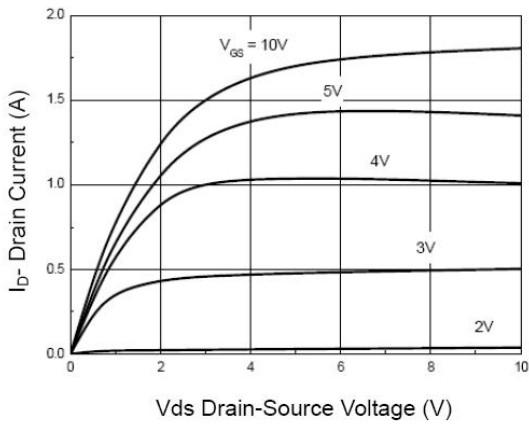


Figure 3 Output Characteristics

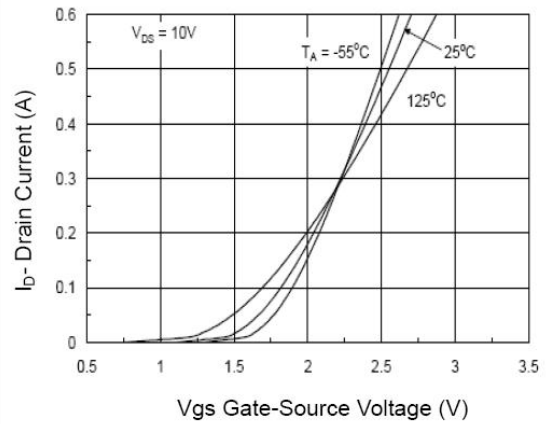


Figure 4 Transfer Characteristics

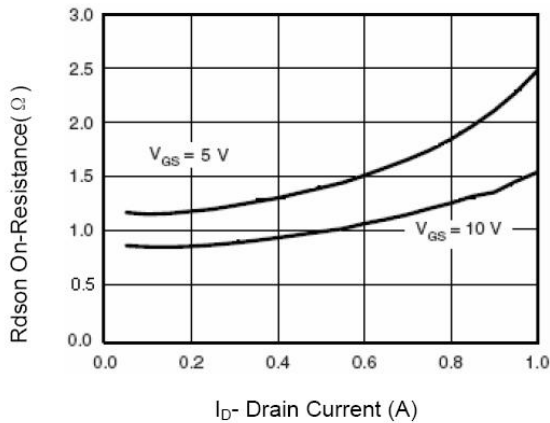


Figure 5 Drain-Source On-Resistance

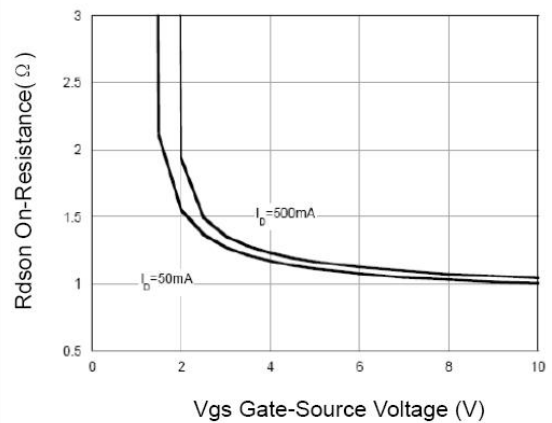


Figure 6 Rdson vs Vgs



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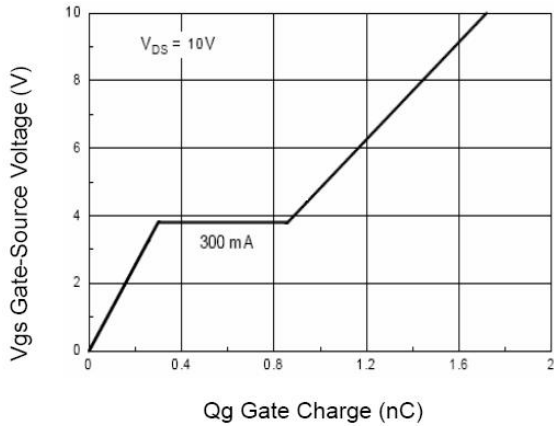


Figure 7 Gate Charge

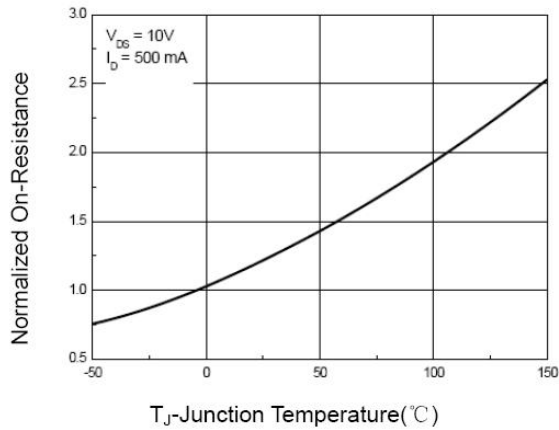


Figure 9 Drain-Source On-Resistance

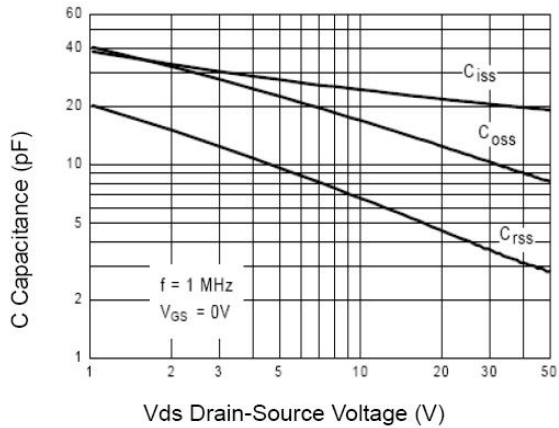


Figure 11 Capacitance vs Vds

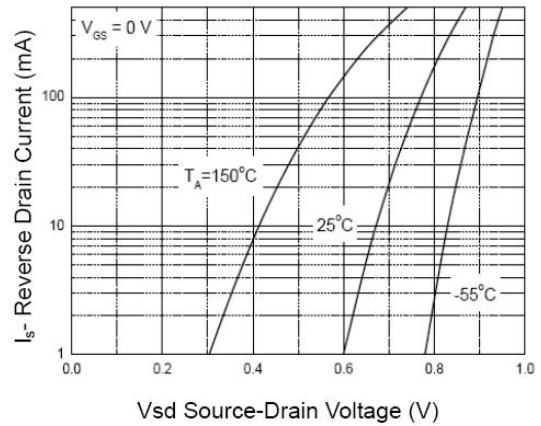


Figure 8 Source-Drain Diode Forward

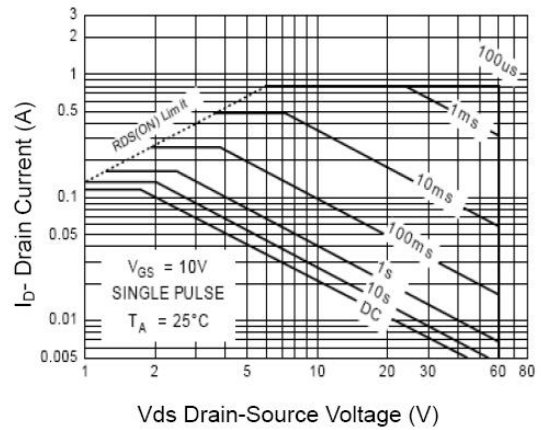


Figure 10 Safe Operation Area



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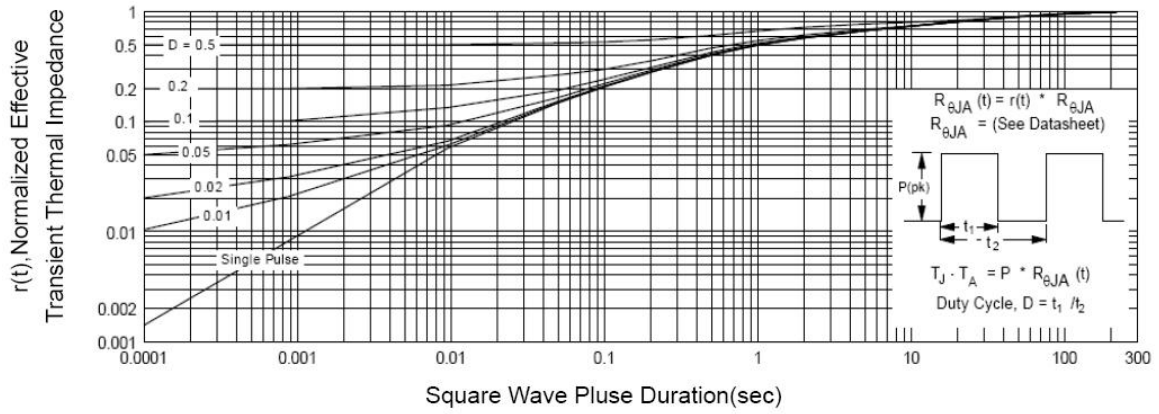


Figure 12 Normalized Maximum Transient Thermal Impedance